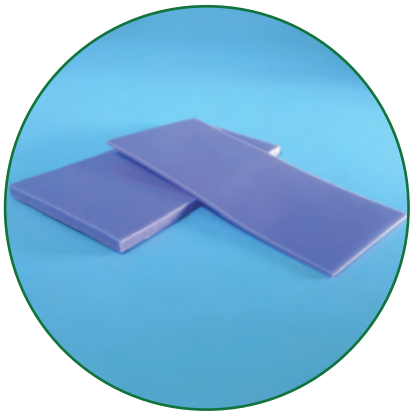
Thermal Pad
CPLK Series

NEW

Silicone-Free

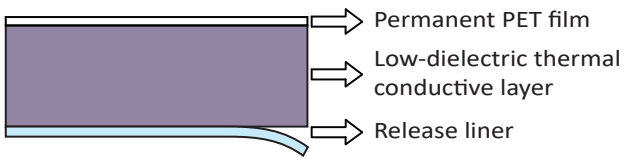
RoHS Compliant



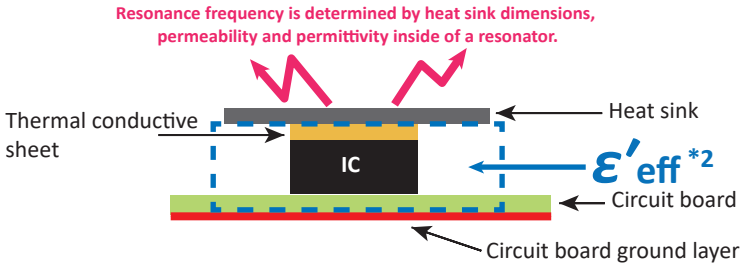
Noise suppression thermally conductive sheet

- Noise level is lowered at low-frequencies compared with conventional thermally conductive sheets
- Low-dielectric thermally conductive sheet helps to reduce noise in GHz bands, which occurs by heat sink's resonance phenomena
- Silicone-free THERMAL PAD contains no siloxane gas and oil bleeding is reduced

Cross-section view



Resonance Phenomena



The smaller the real part of the permittivity is the lower the radiation is at frequencies except resonance.

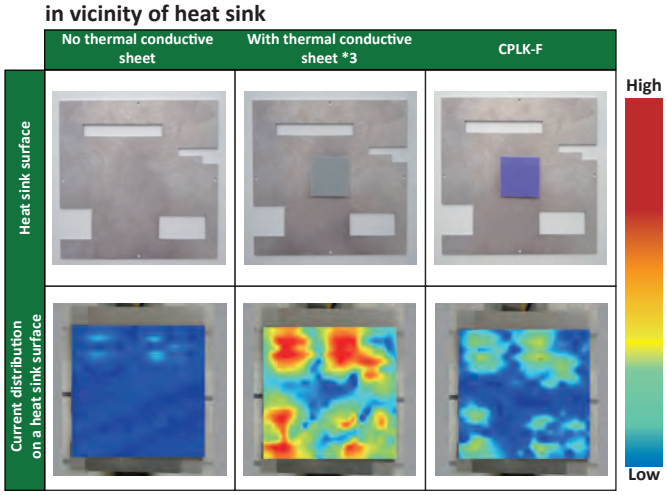
Properties

Part Number	CPLK-F
Thickness (mm)	1.0,1.5,2.0
Available Max Dimension** (mm)	200 x 500
Thermal Conductivity (W/m•K) *JIS R 2616 Hot-wire method	2.0
Thermal Conductivity (W/m•K) *ISO22007-2 Hot-disc method	1.4
Hardness (ASKER C) *JIS K 7312	30
Hardness (Shore 00)*ASTM D 2240	60
Tensile Strength (MPa) *JIS K 6251	0.39
Elongation Rate (%) *JIS K 6251	9.1
Volume Resistivity (Ω • cm) *JIS K 6911	1.0 X 10^{11}
Flame Resistance *UL94	V-0 equivalent
Operating Temperature (°C)	-40 ~ 125
Color	Mauve
Loss Tangent (500 MHz) *Company Standard	0.17
Loss Tangent (1 GHz) *Company Standard	0.13
Relative Permittivity(500 MHz) *Company Standard	4.51
Relative Permittivity(1 GHz) *Company Standard	4.46
Breakdown Voltage (kV/mm) *JIS C 2110-1	6.6
Withstanding Voltage (kV/mm) *JIS C 2110-1	3.0
Specific Gravity *JIS Z 8807	2.0

*TEST METHOD **Please contact us for available pcs/sheet

Effects of Dielectric (measured)

1.0 GHz ~ 1.2 GHz Magnetic field intensity in vicinity of heat sink



*2 ε'eff: Equivalent relative permittivity between a heat sink and a ground layer of a circuit board

*3 Relative permittivity: ε'= 35

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Please request for detailed product specification data prior to purchase